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(54) Title: SEMICONDUCTOR DEVICE HAVING A SEMICONDUCTOR CHIP ELECTRICALLY CONNECTED TO A WIRING SUBSTRATE

(57) Abstract

A semiconductor device comprising a semiconductor chip, a wiring substrate, and an adhesive preferably containing electroconductive particles interposed therebetween, a plurality of spacer elements being present on or below the adhesive layer, said spacer elements having almost the same height as surrounding projecting electrodes and at least one shape selected from circles and polygons when viewed from the top, within an area surrounded by the connected electrodes, has a high flexural strength and high reliability and can be used for information cards, and the like.





